

RJ45G1 R1V 3.3N4YG/YG TY

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

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Germany

www.weidmueller.com



RJ45 transmitter sockets (magnetics) for gigabit applications (1000 base-T) with integrated compensation actively counteracts inductive and capacitive couplings and saves space on the PCB.

The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Transmission rates of up to 1 Gbps
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength ≥ 1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength ≥ 1500 V AC (peak value) or ≥ 1500 V DC according to IEC 60603
- Compliance with IEEE 802.3 requirements (1000Base-T, 1 Gbps, IEEE 802.3ab or 100Base-Tx, 100 Mbps, IEEE 802.3u)

Properties and advantages:

- Extended temperature range of -40 °C to $+85$ °C for maximum performance
- Reinforced gold layer (30μ) for improved corrosion protection

- At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks transformer, 1000 Mbps, THT/THR solder connection, 180°, Shield tabs: none, $30\ldots 80 \mu\text{m}$ Ni / $\geq 30 \mu\text{m}$ Au, LED: Yes, Green/yellow, Green/yellow, Number of poles: 10, Tray (manual assembly)
Order No.	1534760000
Type	RJ45G1 R1V 3.3N4YG/YG TY
GTIN (EAN)	4050118338423
Qty.	120 pc(s).
Packaging	Tray (manual assembly)

Creation date March 24, 2021 5:10:39 AM CET

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Technical data

Dimensions and weights

Depth	16.8 mm	Depth (inches)	0.661 inch
Height	20.3 mm	Height (inches)	0.799 inch
Height of lowest version	17 mm	Net weight	3.783 g
Width	16 mm	Width (inches)	0.63 inch

System specifications

Colour of left LED	Green/yellow	Colour of right LED	Green/yellow
LED	Yes	Mounting onto the PCB	THT/THR solder connection
Number of poles	10	Number of solder pins per pole	1
Outgoing elbow	180°	Performance-Category	1000 Mbps
Pitch in inches (P)	0.05 inch	Pitch in mm (P)	1.27 mm
Product family	OMNIMATE Data - RJ45 transformer jack	Protection degree	IP20
Shield surface	nickel-plated	Shield tabs	none
Shielding	Yes	Shielding material	Brass
Solder eyelet hole diameter (D)	0.9 mm	Solder eyelet hole diameter tolerance (D) ± 0.1 mm	
Solder pin dimensions	0.40 x 0.30 mm, LED pins = 0.50 x 0.50 mm	Solder pin length (l)	3.2 mm
Soldering process	Reflow soldering, Manual soldering, Wave soldering	Transmission rate	1000 Mbps
Type of connection	Socket connector	Wiring	10-wire

Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Rated current	1.5 A	Rated voltage	125 V

Standards

Connector standard	IEC 60603-7-51
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Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	II
Comparative Tracking Index (CTI)	≥ 500	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact base material	Phosphorus bronze
Contact surface	Gold over nickel	Layer structure of plug contact	30...80 µ" Ni / ≥ 30 µ" Au
Storage temperature, min.	-40 °C	Storage temperature, max.	85 °C
Operating temperature, min.	-40 °C	Operating temperature, max.	85 °C

Packing

Packaging	Tray (manual assembly)	VPE length	25 mm
VPE width	175 mm	VPE height	300 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

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Approvals



ROHS	Conform
UL File Number Search	E471884

Downloads

Engineering Data	STEP
Product Change Notification	PCN PCN
User Documentation	MAN IE GUIDE DE MAN IE GUIDE EN

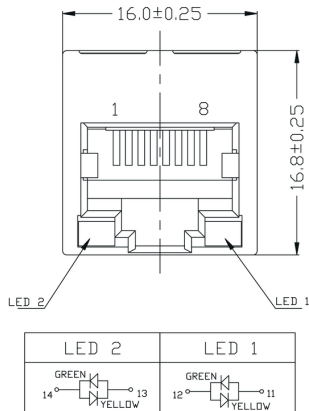
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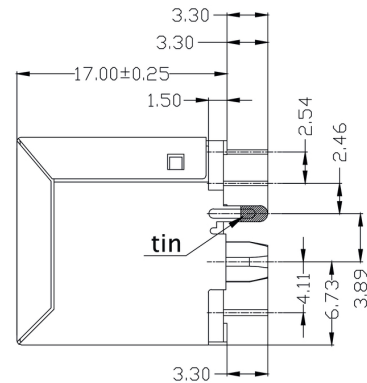
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Drawings

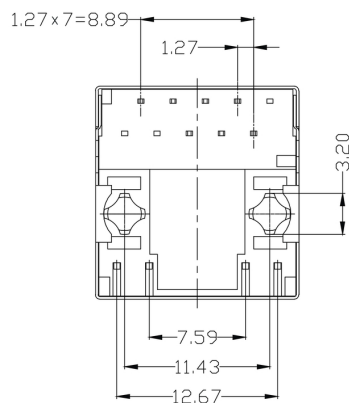
Dimensioned drawing



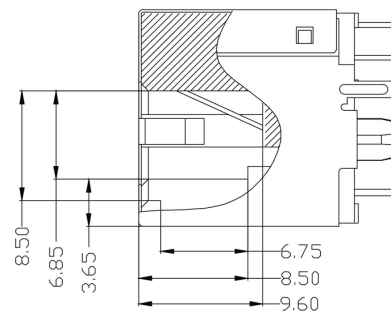
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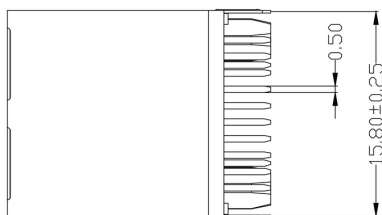
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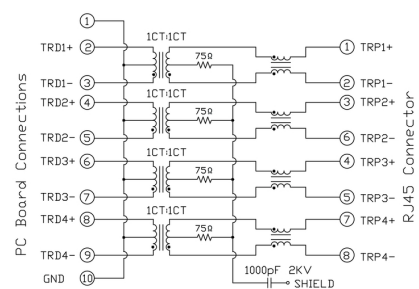
Dimensioned drawing



Dimensioned drawing



Wiring diagram



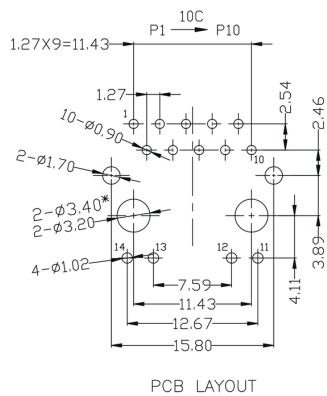
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PCB design



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Drawings

Characteristics

Inductance	350 µH min. @ 100 kHz, 100 mV, 8 mA DC Bias
Leakage Inductance	0.3 µH max. @ 100 kHz, 100 mV
Insertion Loss	1.1 dB max. @ (1 - 100) MHz
Return Loss	18 dB min. @ (1 - 30) MHz 16 dB min. @ (30 - 60) MHz 12 dB min. @ (60 - 80) MHz
Cross Talk	30 dB min. @ (1 - 100) MHz
Common Mode Rejection	30 dB min. @ (1 - 100) MHz

RJ45	G1	R	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY
									Packaging
									TY Tray in box (manual assembly)
									RL Tape on Reel (automated assembly)
									LED
									Y/G Yellow/Green
									G/Y Green/Yellow (standard)
									GY/GY Green-Yellow/Green-Yellow
									O/G Orange/Green
									R/O Red/Orange
									... (further combinations possible)
									N without LED
									Contact surface thickness
									4 1 = 3µ", 2 = 6µ", 3 = 15µ", 4 = 30µ", 5 = 50µ"
									EMI tabs (ground fingers)
									E E = with EMI tabs
									N N = without EMI tabs
									Solder Pin length
									3.2 3.2 mm
									1.6 1.6 mm
									D SMD
									Direction, latch style
									U Horizontal (90°, side entry), latch up
									D Horizontal (90°, side entry), latch down
									V Vertical (180°, top entry)
									Y Diagonal (45°), latch up
									Number of Ports
									1 1 Port
									12; 14; ... multi ports side by side, Multiport
									2; 4; ... multi ports about each other, Multilevel
									Assembly on PCB
									R Through Hole Reflow - THR
									S Soldering process: Wave or Reflow soldering
									S Surface Mount Technology - SMT
									T Soldering process: Reflow soldering
									Through Hole Technology - THT
									Soldering process: Wave
									Performance Category
									C5 Category 5
									C6 Category 6
									C6A Category 6A
									C5e Category 5e
									M 10/100 Mbit
									G1 10/100/1000 Mbit
									G10 10 Gbit
									U Unshielded
									MP 10/100 Mbit with POE
									MP+ 10/100 Mbit with POE+

Type codes

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Catalogue status 12.03.2021 / We reserve the right to make technical changes.

Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.